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November 2013

FQP3N30

N-Channel QFET[®] MOSFET 300 V, 3.2 A, 2.2 Ω

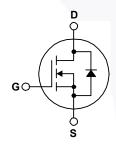
Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 3.2 A, 300 V, $R_{DS(on)}$ = 2.2 Ω (Max.) @ V_{GS} = 10 V, I_D = 1.6 A
- Low Gate Charge (Typ. 5.5 nC)
- · Low Crss (Typ. 6 pF)
- · 100% Avalanche Tested





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQP3N30	Unit
V _{DSS}	Drain-Source Voltage		300	V
I _D	Drain Current - Continuous (T _C = 25°C)		3.2	Α
	- Continuous (T _C = 100	°C)	2.02	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	12.8	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	140	mJ
I _{AR}	Avalanche Current	(Note 1)	3.2	Α
E _{AR}	Repetitive Avalanche Energy (N		5.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5	V/ns
P _D	Power Dissipation (T _C = 25°C)	55	W	
	- Derate above 25°C	0.44	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum Lead Temperature for Solderin 1/8" from Case for 5 seconds	300	°C	

Thermal Characteristics

Symbol	Parameter	FQP3N30	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.27	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQP3N30	FQP3N30	TO-220	Tube	N/A	N/A	50 units

FI	lectrical	Chara	cteristics

Symbol	Parameter	Test Conditions	Min	Тур	Max	Uni
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	300			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		0.35		V/°C
I _{DSS}	Zoro Coto Voltago Drain Current	V _{DS} = 300 V, V _{GS} = 0 V			1	μА
Zero Gate Voltage Drain Curre	Zero Gate Voltage Drain Current	V _{DS} = 240 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 1.6 A		1.65	2.2	Ω
g _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 1.6 A		1.75		S
C _{iss}	Input Capacitance Output Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz		175 40	230 50	pF pF
C _{rss}	Reverse Transfer Capacitance			6	8	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 150 V, I _D = 3.2 A,		10	30	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		40	90	ns
t _{d(off)}	Turn-Off Delay Time			10	30	ns
t _f	Turn-Off Fall Time	(Note 4)	25	60	ns
Qg	Total Gate Charge	V _{DS} = 240 V, I _D = 3.2 A,		5.5	7.0	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		1.5		nC
Q _{gd}	Gate-Drain Charge	(Note 4)		2.5		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				3.2	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				12.8	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 3.2 A			1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 3.2 A,		120		ns
^	· · · ·	dl / dt = 100 A/::-		0.4		_

Q_{rr}

- **Notes:** 1. Repetitive Rating : Pulse width limited by maximum junction temperature. 2. L = 22.5 mH, I_{AS} = 3.2 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C. 3. I_{SD} ≤ 3.2 A, I_{SD} ≤ 3.2 A, I_{SD} ≤ 3.2 A, I_{SD} ≤ 8V_{DSS}, starting I_{SD} = 25°C. 4. Essentially independent of operating temperature.

Reverse Recovery Charge

μС

0.4

 $dI_F / dt = 100 A/\mu s$

Typical Characteristics

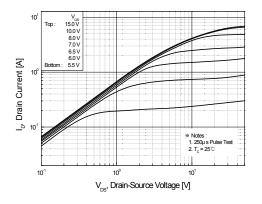


Figure 1. On-Region Characteristics

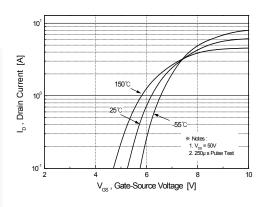


Figure 2. Transfer Characteristics

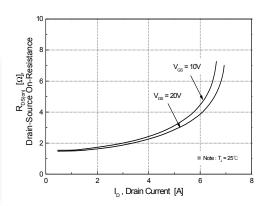


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

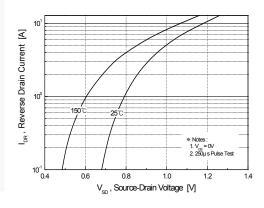


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

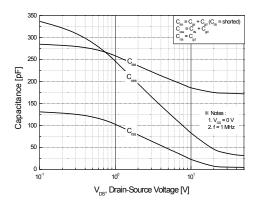


Figure 5. Capacitance Characteristics

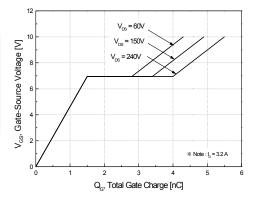


Figure 6. Gate Charge Characteristics

Typical Characteristics (continued)

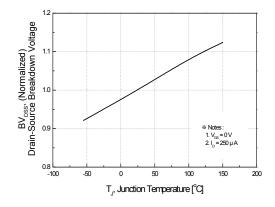
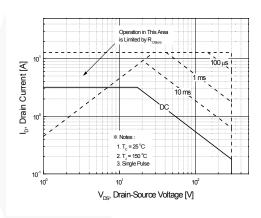


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



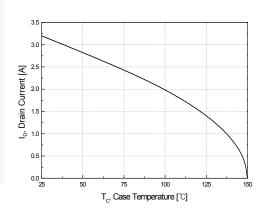


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

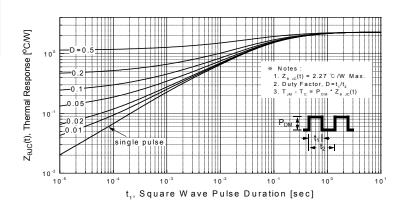


Figure 11. Transient Thermal Response Curve

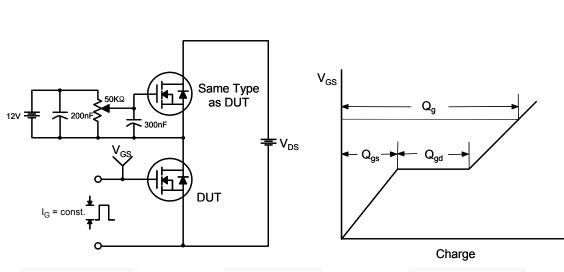


Figure 12. Gate Charge Test Circuit & Waveform

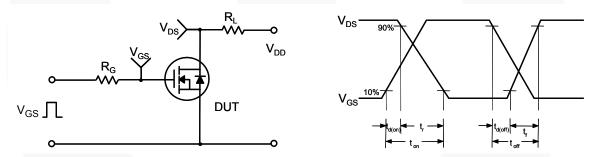


Figure 13. Resistive Switching Test Circuit & Waveforms

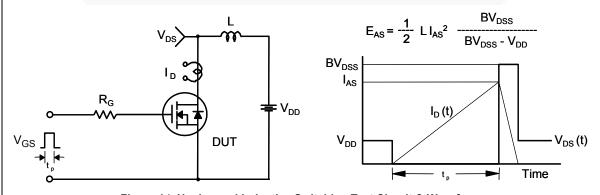
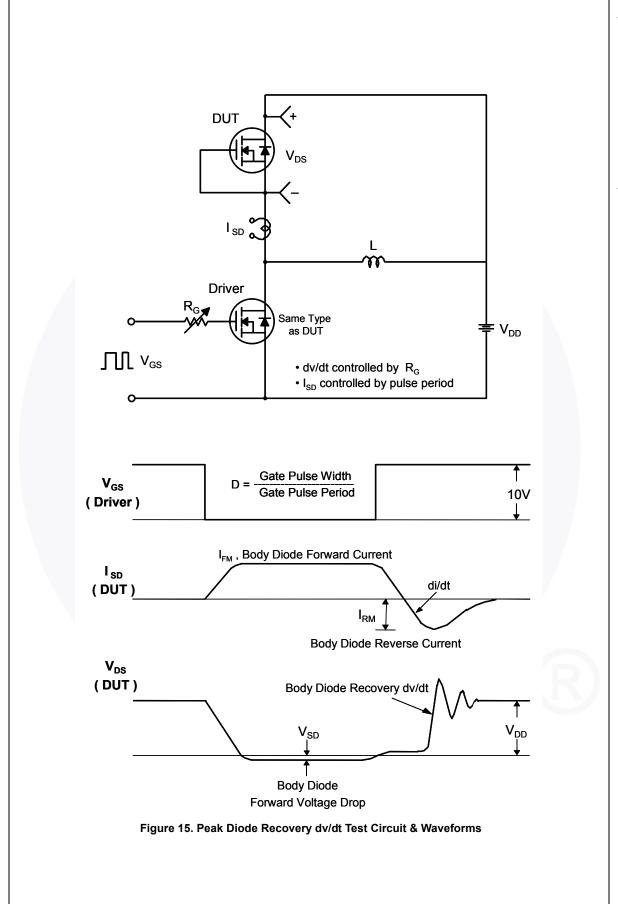


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions

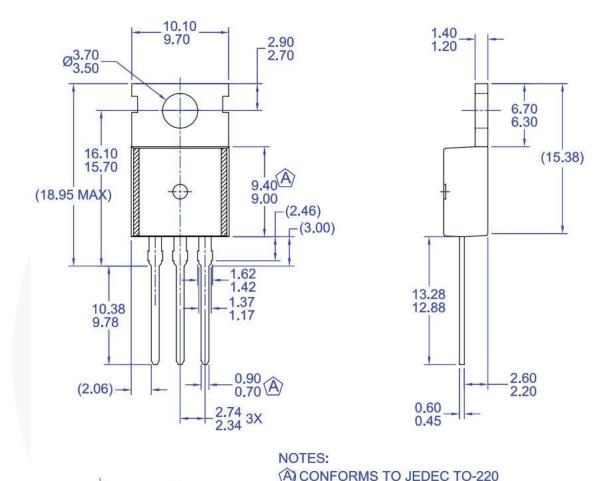


Figure 16. TO220, Molded, 3-Lead, Jedec Variation AB

VARIATION AB EXCEPT WHERE NOTED

C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

D) DRAWING FILE/REVISION: MKT-TO220Y03REV1

B) ALL DIMENSIONS ARE IN MILLIMETERS.

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4.70

4.30





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